



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akihiro OSAKA et al.

Application No.: 10/073,876

Filed: February 14, 2002

Docket No.: 105913.01

For: SEMICONDUCTOR MANUFACTURING METHOD AND SEMICONDUCTOR
MANUFACTURING APPARATUS

RECEIVED

MAR 22 2002

PRELIMINARY AMENDMENT

GROUP 3600

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 4, lines 20-26, delete current paragraph and insert therefor:

B1
The invention of the first aspect is a semiconductor manufacturing method including a
step of detecting the position of the orientation flat or notch of a substrate and aligning to a
specific position, wherein a substrate transfer unit that transfers substrates to a processing
chamber or processing jig is used for the orientation flat or notch alignment of the substrates.

Page 5, lines 6-10, delete current paragraph and insert therefor:

B2
The invention of the second aspect is the semiconductor manufacturing method
according to the invention of the first aspect, wherein the orientation flat or notch alignment
of the substrates is performed in a transfer chamber in which the substrate transfer unit is
installed.

BEST AVAILABLE COPY

3651
PRE
AMEND
MENT
#4/B
ASW
AUG, 9, 2002